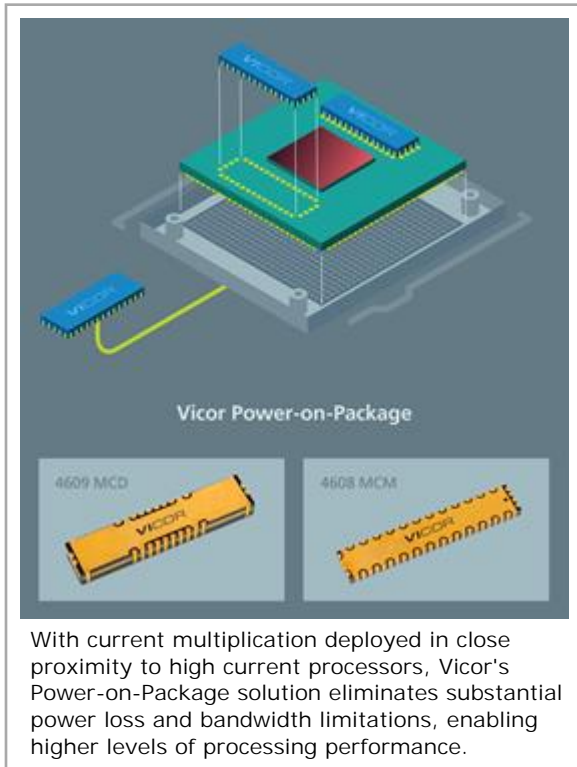




Vicor's Power-on-Package System Provides up to 1,000A Peak Current

March 6, 2018

Enables Higher XPU Performance



ANDOVER, Mass., March 06, 2018 (GLOBE NEWSWIRE) -- Vicor Corporation (NASDAQ:VICR) today announced a new Power-on-Package ("PoP") ChiP-set including Modular Current Multipliers ("MCMs") for high performance GPU, CPU, and ASIC ("XPU") processors. PoP MCMs multiply current and divide voltage from a 48V source in close proximity to XPUs to enable higher levels of XPU performance. Power distribution efficiency and system density rise beyond the limitations of conventional 12V input multi-phase voltage regulators lacking current multiplication. Power-on-Package is an enabling technology for high current Artificial Intelligence ("AI") processors and 48V autonomous driving systems.

Power-on-Package modules build upon Factorized Power Architecture (FPA) systems deployed in high performance computers and large scale datacenters. FPA supports efficient power distribution and direct conversion from 48V to sub-1V XPUs. With current multiplication deployed in close proximity to high current processors, PoP MCMs overcome previous barriers to improved performance.

A pair of MCM4608S59Z01B5T00 (MCMs) and a MCD4609S60E59H0T00 Modular Current Multiplier Driver (MCD) provide 600A continuous and up to 1,000A peak at up to 1V. Owing to their high density, low profile package (46 x 8 x 2.7mm) and low noise attributes, Modular Current Multipliers (MCMs) are suitable for co-packaging within the XPU substrate or adjacent to it. Close proximity to the XPU eliminates substantial power loss and bandwidth limitations incurred in the "last inch" of the current delivery path from the boundaries of 12V multi-phase regulators.

Learn more about [Power on Package Technology](#).

Follow Vicor on Social Media

Twitter: [@VicorPower](#) »

[Vicor Corporation on LinkedIn](#) »

[Vicor PowerBlog](#) »

About Vicor Corporation

Headquartered in Andover, Massachusetts, Vicor Corporation, manufactures and markets innovative, high-performance modular power components, from power modules to semiconductor-centric solutions, to enable customers to efficiently convert and manage power from the power source to the point of load. www.vicorpower.com

Power Component Design Methodology

Vicor's Power Component Design Methodology enables power system designers to reap all of the benefits of modular power component design – predictable component and system functionality and reliability, fast design cycles, and easy system configurability, re-configurability and scaling – while achieving system operating efficiency, power density and economy that rival the best alternative solutions. Utilizing Vicor's [Power System Designer](#), engineers can select from an extensive portfolio of proven Vicor power components to architect, optimize and simulate their complete power system, all the way from their input sources to their points of load. This innovative approach to power system design delivers fast time-to-market and state-of-the-art performance while minimizing the possibility of last minute surprises and delays that so often occur with conventional or custom design methodologies.

Vicor, FPA, MCM and MCD are trademarks of Vicor Corporation.

Contact

Colin Boroski
Rainier Communications
508-475-0025 x 142
cboroski@rainiero.com

A photo accompanying this announcement is available at <http://www.globenewswire.com/NewsRoom/AttachmentNg/5a5f7788-64a6-409b-bf81-7a1a640aa837>



Source: Vicor Corporation